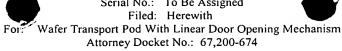


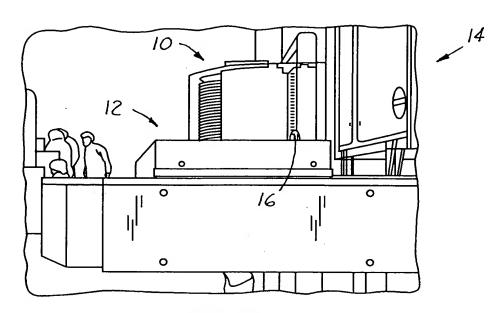
Inventor(s): Tseng, et al Serial No.: To Be Assigned

Filed: Herewith

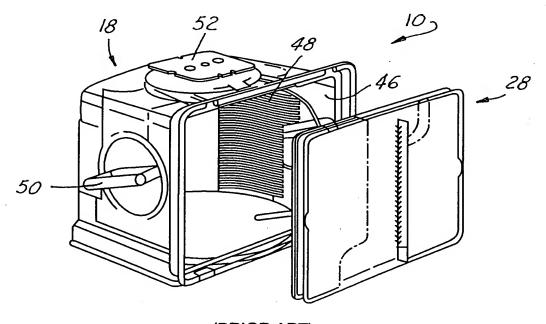


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## (PRIOR ART) FIG 1



(PRIOR ART)
FIG 2



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Filed: Herewith

For: Wafer Transport Pod With Linear Door Opening Mechanism

